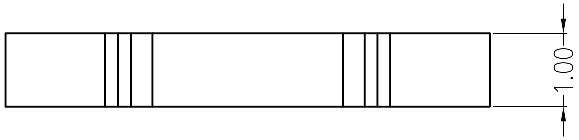
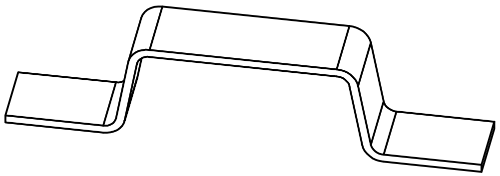
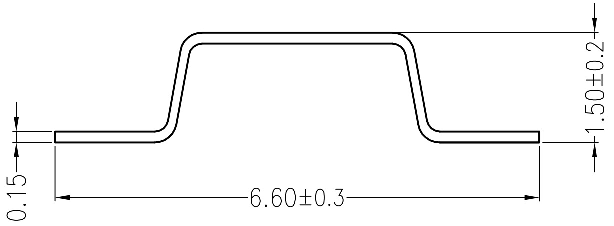
REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	吴丹平	2017.03.23





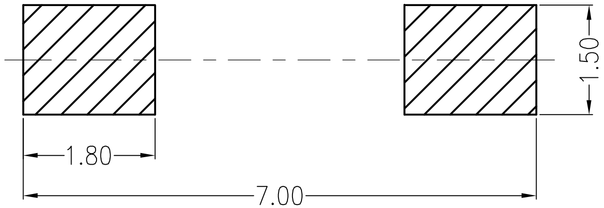


ORDER INFORMATION:

L073B-01-000A1-R

PART No.
No.OF CIRCUITS:
01
PLASTIC MATERIAL:
000=No plastic parts

PACKAGING:
R=REEL
Metal code:
1=PhosphorBronze
PLATING:
A=Sn



Board Layout

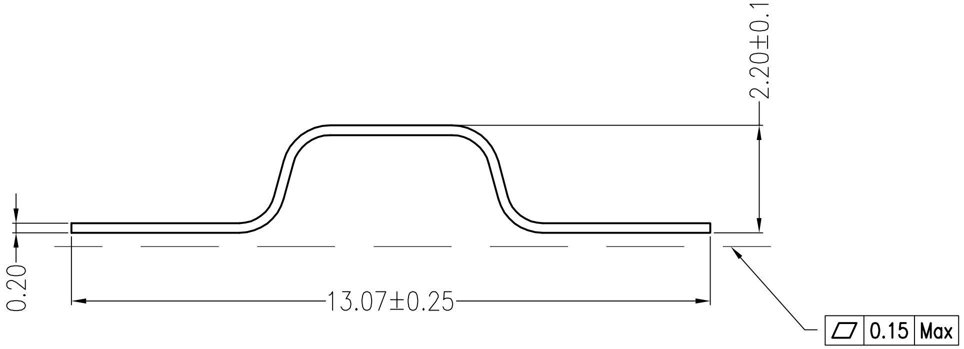
C				
B				
A	CONTACT	1 PCS	PhosphorBronze	Sn-plated
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH

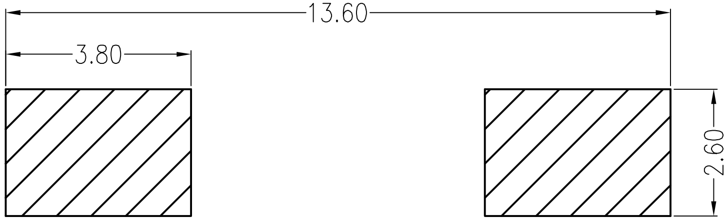
東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TITLE: –

X.±0.5	X.±5°	USE: CUSTOMEP	PART NO.: L073B-01-000A1-R
.X±0.3	.X±2°	APPD: 邵敬和	DWG NO.: GCCP-1023
.XX±0.25	.XX±1°	CHKD: 田峰	SCALE 1 : 1
--	--		SHEET 1 / 1
	UNITS: mm	DR: 吴丹平	

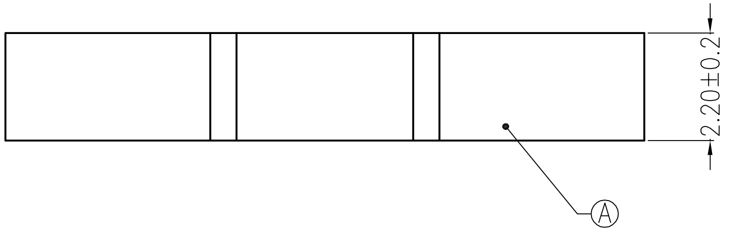
REV	ECN No.	DESCRIPTION	DESIGN	DATE
A	—	Release	蒋建银	2018.01.10





主要技术参数 Main Specifications

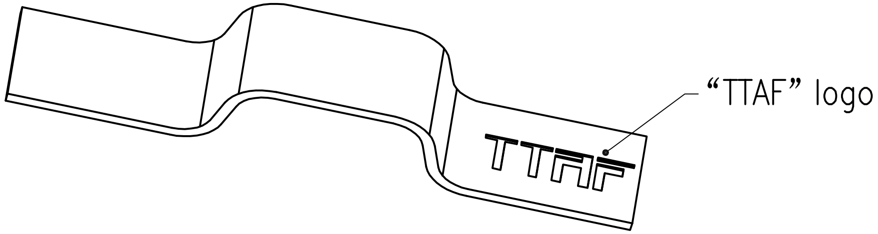
线　　数（Poles): 01
接触电阻（Contact resistance):≤30mΩ
绝缘电阻（Insulation resistance):
额定电压（Rated voltage):250V AC DC
额定电流（Rated current):2.0A AC DC
耐 电 压（Withstand Voltage):
温度范围（Temperature Range）:-40℃～ +125℃



ORDER INFORMATION:

L073K-01-000A1-*

PART No.
No.OF CIRCUITS:
01
PLASTIC MATERIAL:
000=No plastic parts
PACKAGING:
R=REEL
P=PE
Metal code:
1=PhosphorBronze
PLATING:
A=Sn



C					
B					
A	CONTACT		1 PCS	PhosphorBronze	Sn-plated
ITEM	COMPONENT		Q'TY	MATERIAL	FINISH

東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TITLE: L073K
180°wafer smt type

.X±0.35	X.±	USE: CUSTOMER	PART NO.: L073K-01-000A1-R
.XX±0.25	.X±	APPD: 邵敬和	DWG NO.: GCCP-0430
.XXX±0.15	.XX±	CHKD: 田　峰	SCALE 1 : 1
--	--	DR: 蒋建银	SHEET 1 / 1
	UNITS: mm		